

Title (en)
DIELECTRIC INK COMPOSITION

Title (de)
DIELEKTRISCHE TINTENZUSAMMENSETZUNG

Title (fr)
COMPOSITION D'ENCRE DIÉLECTRIQUE

Publication
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Application
EP 18801698 A 20180514

Priority
• US 201762506095 P 20170515
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Abstract (en)
[origin: WO2018213161A1] The present invention relates to flexible and stretchable UV and thermally curable dielectric ink compositions that can be thermo or vacuum formed. The flexible ink can form a stretchable dielectric coating having excellent adhesion. The dielectric ink compositions can be applied on a circuit board, such as a paper-phenolic resin board, plastic board (PMMA, PET or the like) or a glass-epoxy resin board, by screen printing or the like, followed by heat/UV curing. The compositions are suitable for use in applications such as a capacitive touch, in-mold forming, creating cross over insulation layers, and manufacturing electronic circuitry and devices.

IPC 8 full level
C09D 11/101 (2014.01)

CPC (source: EP US)
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C-Set (source: US)
C09D 11/10 + C09D 11/52

Citation (search report)
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• See also references of WO 2018213161A1

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Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
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